IN THE SPECIFICATION

Please amend the specification as indicated below:

New par. -- [0028A]: FIG. 2E illustrates features of a system in accordance with an embodiment of the present invention; --

In par. [0034]: -- FIG. 2A schematically depicts the general inventive concept of reticle stage calibration process 200, constructed and operative in accordance with a particular embodiment of the present invention. Process 200 may be executed by a processing mechanism PROC in connection with the lithographic system, as indicated by FIG. 2E. As discussed in greater detail below, processing mechanism PROC may be configured to decompose height offsets, determine reticle RE deformation attributes, and determine reticle stage RS deformation attributes. As indicated in FIG. 2A, process 200 commences with procedure task P202, which images reticle RE to generate a set of reticle height offsets. That is, a projection beam PB of radiation is passed through the reticle RE to generate an image of the pattern on the reticle RE. In one embodiment, the exposure may be performed to generate a "floating z-map" of height offsets. In general, a z-map provides a collection of reticle height offsets, which indicate the changes in the z direction due to the various components encountered between the reticle RE and wafer substrate W. As such, these offsets collectively represent focal distortions attributable to the various components, including reticle RE and reticle stage RS distortions. --

In par. [0053]: -- x,y_{sl}: the position of TIS sensor in x,y; --.

In par. [0055]: -- z_θ z_{0sl}: the height offset of TIS; ; z_{0rs}: lens, the height offset of the reticle; ; and; z_{0rs}: the height offset of the reticle stage; --.

In par. [0089]: -- FC_{TIS} FC_{xTIS}: the 2nd order warp distortion of the TIS plate in x; and FC_{yTIS}: the 2nd order warp distortion of the TIS plate in y.

IN THE DRAWINGS

Applicants hereby submit replacement sheet of FIG. 1A and new FIG. 2E with the filing of this amendment.